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This report is broken up into 12 chapters:
- Chapter 1 - Welcome
- Chapter 2 - The Packaging Market and History
- Chapter 3 - Package Types
- Chapter 4 - Packaging Process Overview
- Chapter 5 - Wafer Level and Multi Chip Packaging
- Chapter 6 - Green Packages
- Chapter 7 - Packaging Materials
- Chapter 8 - Packaging Costs
- Chapter 9 - Test
- Chapter 10 - Qualification
- Chapter 11 - Selecting and Managing Packaging Foundries
- Chapter 12 - Profiles of the Top Ten OSATs

1.7. What This Report is Not
This report is meant to give the reader an understanding of integrated circuit packaging trends.
- We discuss general market trends, but this is not a market research firm and we are not in the business of forecasting the market. For market research and forecasts we recommend IC Insights at www.icinsights.com.
- This report presents some discussion of packaging costs, for detailed packaging costs we recommend or IC Cost and Price Model.

1.8. About The Author
Frank Muscolino is a packaging industry insider with over 20 years of experience. Frank has served in a variety of engineering, management and sales positions within the industry including sales manager for one of the ten largest packaging foundries. Frank has a Masters Degree in Chemistry from Clarkson University.